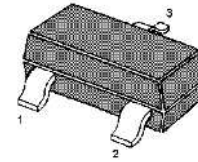
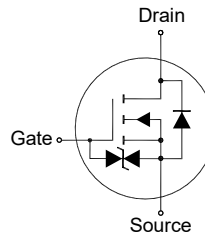


N-Channel Enhancement Mode MOSFET
Features

- AEC-Q101 Qualified
- Low on resistance $R_{DS(ON)}$
- Low gate threshold voltage
- Low input capacitance
- Halogen and Antimony Free(HAF), RoHS compliant
- Typical ESD Protection HBM Class 2


 1.Gate 2.Source 3.Drain
SOT-23 Plastic Package

| Classification | Voltage Range(V) |
|----------------|------------------|
| 0A | < 125 |
| 0B | 125 to < 250 |
| 1A | 250 to < 500 |
| 1B | 500 to < 1000 |
| 1C | 1000 to < 2000 |
| 2 | 2000 to < 4000 |
| 3A | 4000 to < 8000 |
| 3B | ≥ 8000 |

Application

- Portable appliances
- Battery management

Absolute Maximum Ratings (at $T_a = 25^\circ\text{C}$ unless otherwise specified)

| Parameter | Symbol | Value | Unit |
|--|----------------|---------------|------|
| Drain-Source Voltage | V_{DS} | 60 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Drain Current (Steady State 1sq in pad) ¹⁾ | I_D | 380 270 | mA |
| Drain Current (Steady State Minimum pad) ²⁾ | I_D | 320 230 | mA |
| Peak Drain Current, Pulsed ($t_p = 10 \mu\text{s}$) | I_{DM} | 1.5 | A |
| Total Power Dissipation ²⁾ | P_{tot} | 350 | mW |
| Operating and Storage Temperature Range | T_j, T_{stg} | - 55 to + 150 | °C |

Thermal Characteristics

| Parameter | Symbol | Value | Unit |
|--|-----------------|-------|------|
| Thermal Resistance-Junction to Ambient ²⁾ | $R_{\theta JA}$ | 357 | °C/W |

¹⁾ Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.

²⁾ Device mounted on FR-4 substrate PC board, with minimum recommended pad layout.

Characteristics at $T_a = 25^\circ\text{C}$ unless otherwise specified

| Parameter | Symbol | Min. | Typ. | Max. | Unit |
|--|--------------|--------|--------|----------|---------------|
| STATIC PARAMETERS | | | | | |
| Drain Source Breakdown Voltage at $I_D = 10 \mu\text{A}$ | BV_{DSS} | 60 | - | - | V |
| Zero Gate Voltage Drain Current at $V_{DS} = 60 \text{ V}$ | I_{DSS} | - | - | 1 | μA |
| Gate Source Leakage Current at $V_{GS} = \pm 20 \text{ V}$ | I_{GSS} | - | - | ± 10 | μA |
| Gate Threshold Voltage at $V_{DS} = 10 \text{ V}$, $I_D = 250 \mu\text{A}$ | $V_{GS(th)}$ | 1 | - | 2.5 | V |
| Static Drain Source On-Resistance at $V_{GS} = 10 \text{ V}$, $I_D = 500 \text{ mA}$ at $V_{GS} = 4.5 \text{ V}$, $I_D = 200 \text{ mA}$ | $R_{DS(ON)}$ | - - | - - | 3 4 | Ω |
| DYNAMIC PARAMETERS | | | | | |
| Forward Transconductance at $V_{DS} = 10 \text{ V}$, $I_D = 200 \text{ mA}$ | g_{FS} | 80 | - | - | mS |
| Gate Resistance at $V_{GS} = 0 \text{ V}$, $V_{DS} = 0 \text{ V}$, $f = 1 \text{ MHz}$ | R_g | - | 200 | - | Ω |
| Input Capacitance at $V_{GS} = 0 \text{ V}$, $V_{DS} = 25 \text{ V}$, $f = 1 \text{ MHz}$ | C_{iss} | - | 22.5 | 50 | pF |
| Output Capacitance at $V_{GS} = 0 \text{ V}$, $V_{DS} = 25 \text{ V}$, $f = 1 \text{ MHz}$ | C_{oss} | - | 12 | 25 | pF |
| Reverse Transfer Capacitance at $V_{GS} = 0 \text{ V}$, $V_{DS} = 25 \text{ V}$, $f = 1 \text{ MHz}$ | C_{rss} | - | 0.5 | 10 | pF |
| Gate charge total at $V_{DS} = 10 \text{ V}$, $I_D = 0.5 \text{ A}$, $V_{GS} = 4.5 \text{ V}$ | Q_g | - | 0.44 | - | nC |
| Gate to Source Charge at $V_{DS} = 10 \text{ V}$, $I_D = 0.5 \text{ A}$, $V_{GS} = 4.5 \text{ V}$ | Q_{gs} | - | 0.2 | - | nC |
| Gate to Drain Charge at $V_{DS} = 10 \text{ V}$, $I_D = 0.5 \text{ A}$, $V_{GS} = 4.5 \text{ V}$ | Q_{gd} | - | 0.1 | - | nC |
| Turn-On Delay Time at $V_{DS} = 30 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 0.5 \text{ A}$, $R_g = 25 \Omega$ | $t_{d(on)}$ | - | 2.7 | - | ns |
| Turn-On Rise Time at $V_{DS} = 30 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 0.5 \text{ A}$, $R_g = 25 \Omega$ | t_r | - | 2.5 | - | ns |
| Turn-Off Delay Time at $V_{DS} = 30 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 0.5 \text{ A}$, $R_g = 25 \Omega$ | $t_{d(off)}$ | - | 13 | - | ns |
| Turn-Off Fall Time at $V_{DS} = 30 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 0.5 \text{ A}$, $R_g = 25 \Omega$ | t_f | - | 8 | - | ns |
| Body-Diode PARAMETERS | | | | | |
| Drain-Source Diode Forward Voltage at $V_{GS} = 0 \text{ V}$, $I_S = 0.5 \text{ A}$ | V_{SD} | - | 0.85 | - | V |
| Body Diode Reverse Recovery Time at $I_S = 0.5 \text{ A}$, $di/dt = 100 \text{ A} / \mu\text{s}$ | t_{rr} | - | 30 | - | ns |
| Body Diode Reverse Recovery Charge at $I_S = 0.5 \text{ A}$, $di/dt = 100 \text{ A} / \mu\text{s}$ | Q_{rr} | - | 29 | - | nC |

Electrical Characteristics Curves

Fig. 1 Typical Output Characteristics

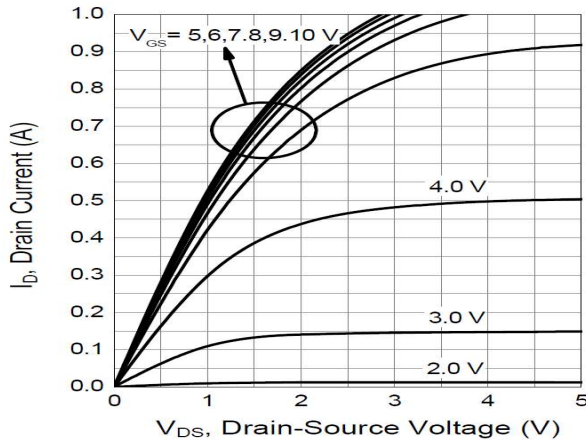


Fig. 2 Typical Transfer Characteristics

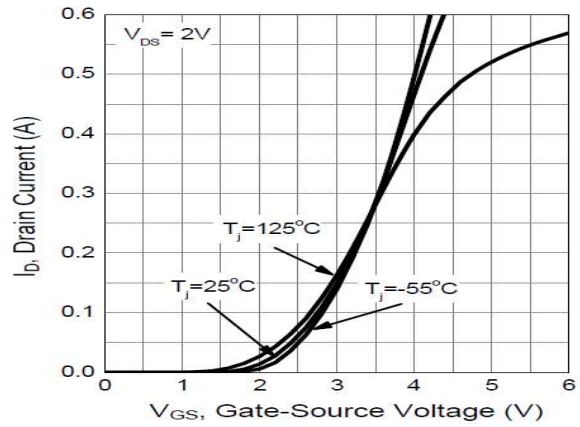


Fig. 3 $R_{DS(on)}$ vs. Gate-Source Voltage

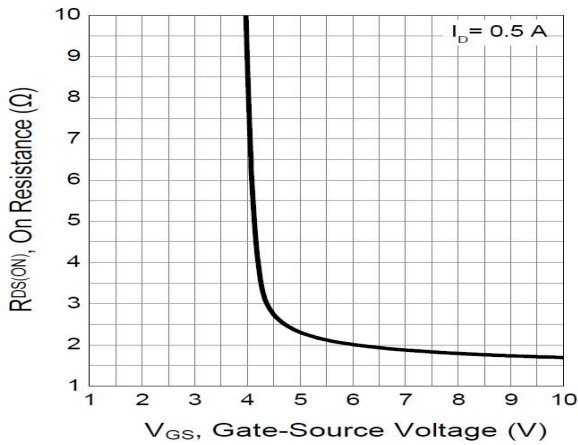


Fig. 4 on-Resistance vs. T_J

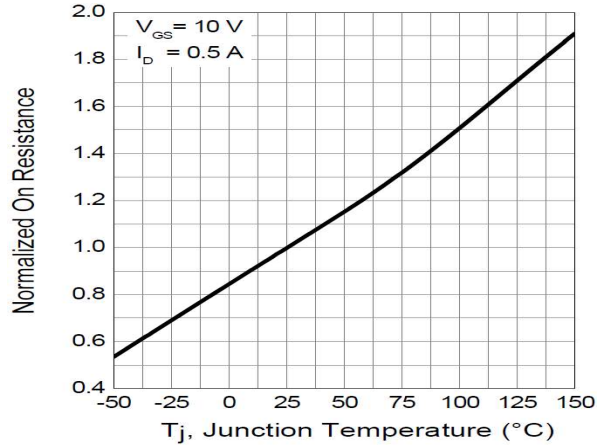


Fig. 5 on-Resistance vs. Drain Current

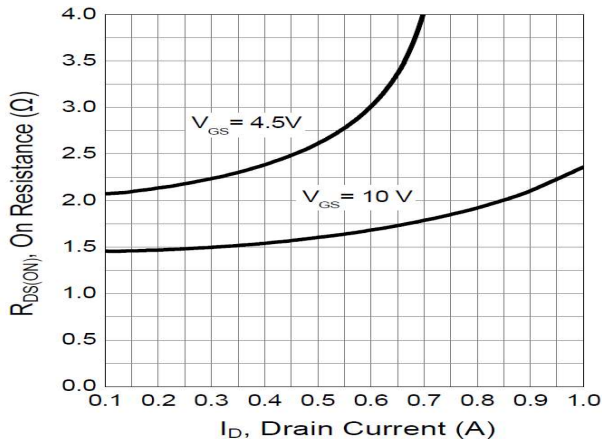
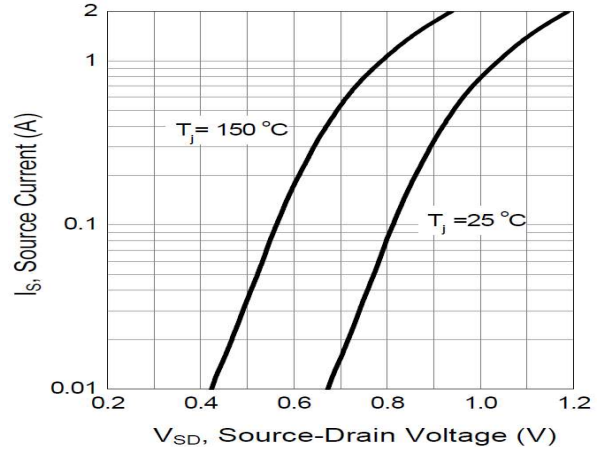


Fig. 6 Typical Forward Characteristics



Electrical Characteristics Curves

Fig. 7 Typical Junction Capacitance

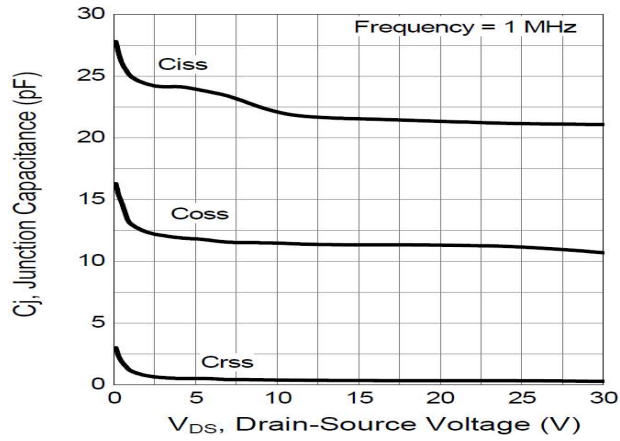


Fig. 8 Gate Threshold Variation vs. T_j

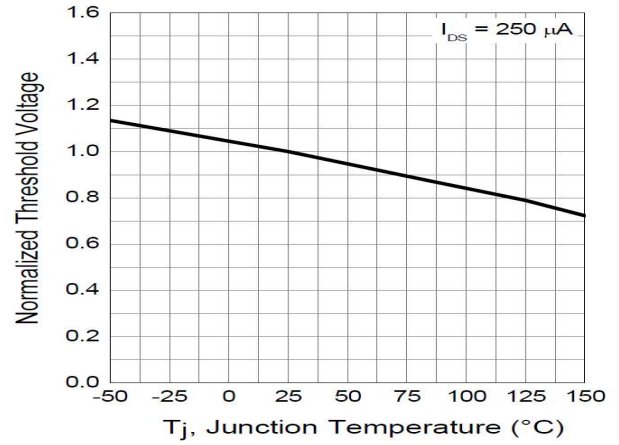
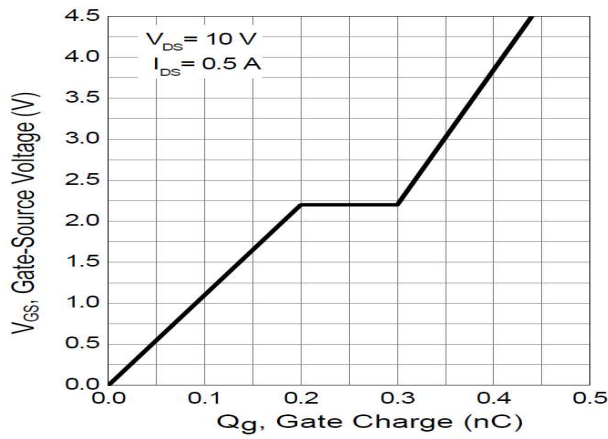


Fig. 9 Gate Charge



Test Circuits

Fig.1-1 Switching times test circuit

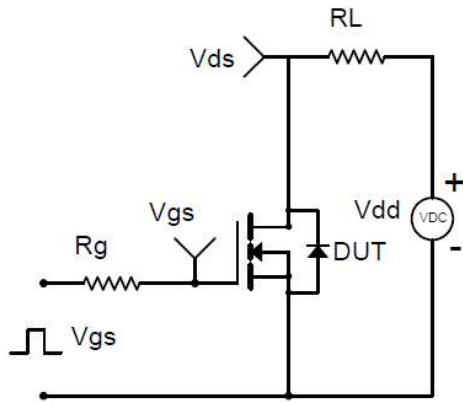


Fig.1-2 Switching Waveform

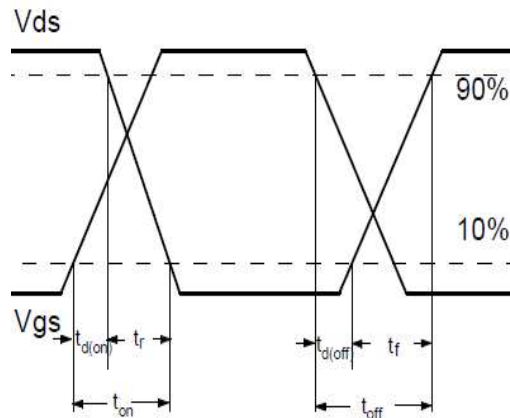


Fig.2-1 Gate charge test circuit

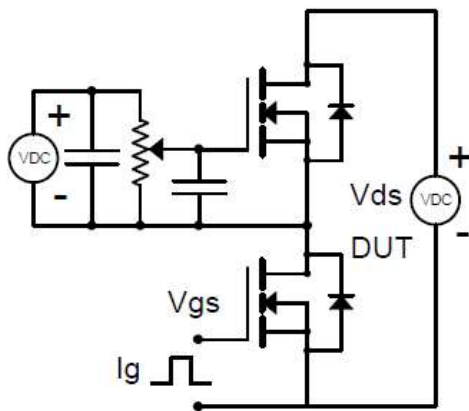
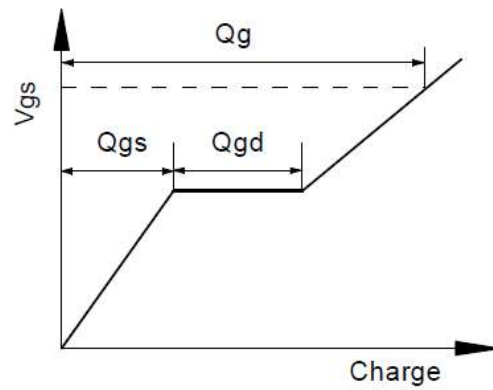
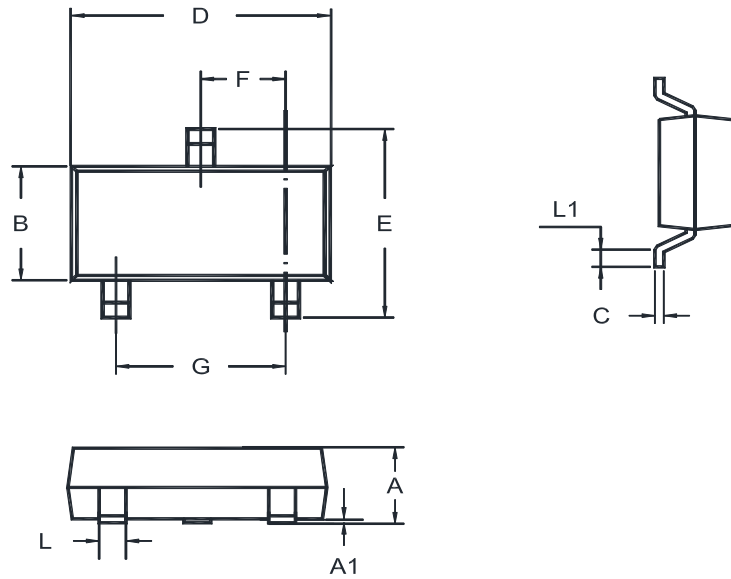
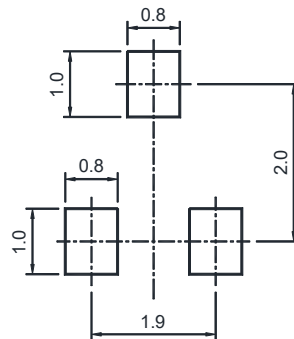


Fig.2-2 Gate charge waveform



Package Outline (Dimensions in mm)
SOT-23


| Unit | A | A1 | B | C | D | E | F | G | L | L1 |
|------|--------------|----------------|--------------|--------------|--------------|------------|--------------|--------------|--------------|------------|
| mm | 1.20 0.89 | 0.100 0.013 | 1.40 1.20 | 0.19 0.08 | 3.04 2.80 | 2.6 2.2 | 1.02 0.89 | 2.04 1.78 | 0.51 0.37 | 0.2 MIN |

Recommended Soldering Footprint

Packing information

| Package | Tape Width (mm) | Pitch | | Reel Size | | Per Reel Packing Quantity |
|---------|-----------------|---------|---------------|-----------|------|---------------------------|
| | | mm | inch | mm | inch | |
| SOT-23 | 8 | 4 ± 0.1 | 0.157 ± 0.004 | 178 | 7 | 3,000 |

Marking information

" K72 " = Part No.

" • " = HAF (Halogen and Antimony Free)

"YM" = Date Code Marking

"Y" = Year

"M" = Month

Font type: Arial

